



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
 [List multiple models if applicable.]

Name / Model #1: HP t5325 Thin Clients

Name / Model #2

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Phillips screwdriver	
Description #2 Dikes	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. To remove the rear cover (see Figure 1):
 - a. On rear of the thin client, remove the screw that secures the cover to the unit (1).
 - b. Slide the cover downward (2).
 - c. Remove the cover from the unit..
2. To remove the side panel, slide the panel about 13 mm (1/2 inch) toward the top of the unit, and then lift the access panel up and off the unit (see Figure 2).
3. To remove the battery, gently push the metal guard that extends above one edge of the battery slightly toward the rear of the unit (1), and then lift the battery out (2) (see Figure 3).
4. To remove the system board:
 - a. On the rear of the unit, remove the two hex screws from each side of the DVI connector (see Figure 4).
 - b. Remove the two screws that secure the rear I/O panel to the unit (see Figure 5).
 - c. Pull the rear I/O panel off the unit.
 - d. Remove the four screws that secure the system board to the unit (see Figure 6).
 - e. Slide the system board out of the unit.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

FIGURE 1: Removing the rear cover



FIGURE 2: Removing the side panel



FIGURE 3: Battery removal

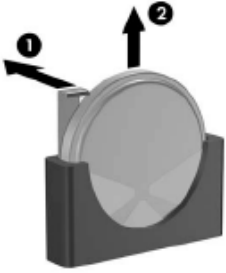


FIGURE 4: Hex nut screw locations



FIGURE 5: Rear I/O panel screw locations

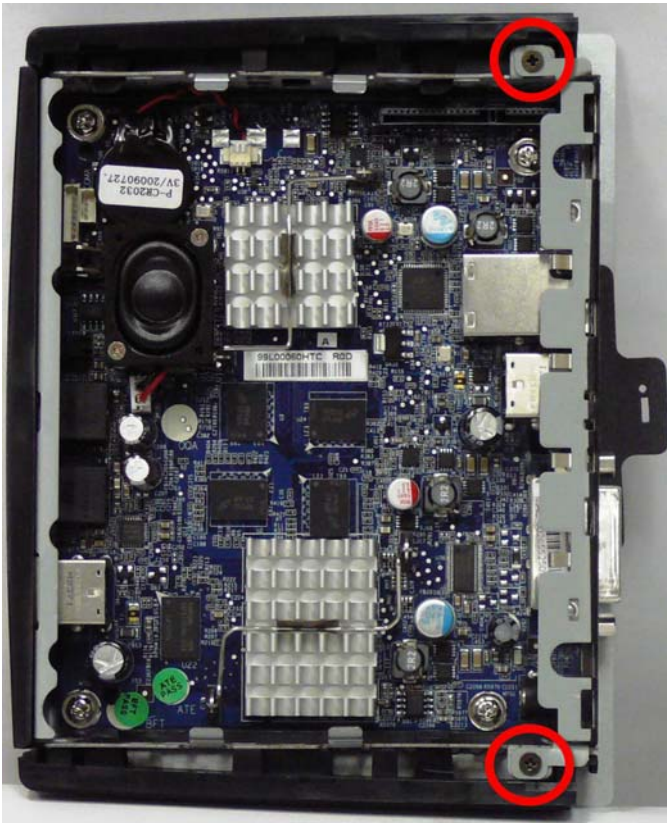


FIGURE 6: System board screw locations

